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STPS20M60C

Power Schottky rectifier

Features

- High current capability
- Avalanche rated
- Low forward voltage drop
- High frequency operation

Description

The STPS20M60C is a dual diode Schottky rectifier, suited for high frequency switch mode power supply.

Packaged in TO-220AB, I²PAK and D²PAK, this device is intended to be used in notebook, game station and desktop adapters, providing in these aplications a good efficiency at both low and high load.

Table 1. Device summary

Symbol	Value
I _{F(AV)}	2 x 10 A
V _{RRM}	60 V
V _F (typ)	0.370 V
T _j (max)	150 °C

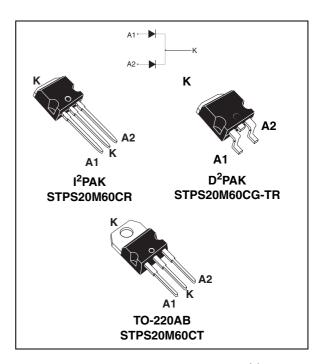
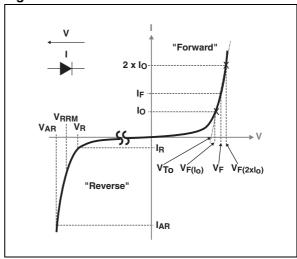


Figure 1. Electrical characteristics^(a)



V_{ARM} and I_{ARM} must respect the reverse safe operating area defined in *Figure 12*. V_{AR} and I_{AR} are pulse measurements (t_p < 1 μs). V_R, I_R, V_{RRM} and V_F, are static characteristics

Characteristics STPS20M60C

1 Characteristics

Table 2. Absolute ratings (limiting values, per diode, at $T_{amb} = 25$ °C unless otherwise specified)

Symbol	Parameter				Value	Unit
V_{RRM}	Repetitive peak reverse vol	Repetitive peak reverse voltage			60	V
I _{F(RMS)}	Forward rms current				40	Α
I _{F(AV)}	Average forward current, δ	Average forward current, $\delta = 0.5$ $ T_{c} = 140 ^{\circ}\text{C} \text{Per diode} $ $ T_{c} = 135 ^{\circ}\text{C} \text{Per device} $				Α
I _{FSM}	Surge non repetitive forward current $t_p = 10 \text{ ms sinusoidal}$			300	Α	
P _{ARM} ⁽¹⁾	Repetitive peak avalanche power $T_j = 25$ °C, $t_p = 1 \mu s$			13600	W	
V _{ARM} ⁽²⁾	Maximum repetitive peak avalanche voltage	t _p < 1 μs, T _j < 150 °C, I _{AR} < 51 A			80	V
V _{ASM} ⁽²⁾	Maximum single-pulse peak avalanche voltage	' IT < I IIS 1 < 150 °C 145 < 51 A			80	V
T _{stg}	Storage temperature range			-65 to +175	°C	
Tj	Maximum operating junction temperature ⁽³⁾			150	°C	

^{1.} For temperature or pulse time duration deratings, please refer to *Figure 4* and *5*. More details regarding the avalanche energy measurements and diode validation in the avalanche are provided in the application notes AN1768 and AN2025.

Table 3. Thermal parameters

Symbol	Parameter	Value	Unit	
D	Junction to case	er diode	1.5	°C/W
R _{th(j-c)}		total		C, VV
R _{th(c)}	Coupling		0.2	°C/W

When the two diodes 1 and 2 are used simultaneously:

$$\Delta T_j$$
(diode 1) = P(diode 1) x $R_{th(j-c)}$ (Per diode) + P(diode 2) x $R_{th(c)}$

^{2.} See Figure 12

^{3.} $\frac{dPtot}{dTj} < \frac{1}{Rth(j-a)}$ condition to avoid thermal runaway for a diode on its own heatsink

STPS20M60C Characteristics

Table 4. Static electrical characteristics (per	r diode)
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Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
I _R ⁽¹⁾	Reverse leakage current	T _j = 25 °C	V - V	-	15	65	μΑ
'R`	IR' / Reverse leakage current	T _j = 125 °C	$V_R = V_{RRM}$	-	10	40	mA
		T _j = 25 °C	1 - 5 ^	-	0.465	0.500	
V _F ⁽²⁾ Forward voltage drop	T _j = 125 °C	I _F = 5 A	-	0.370	0.410	V	
	orward voltage drop	T _j = 25 °C	I _F = 10 A	-	0.525	0.570	V
	T _j = 125 °C	I F = I U A	-	0.450	0.510		

- 1. Pulse test: t_p = 5 ms, δ < 2 %
- 2. Pulse test: t_p = 380 μ s, δ < 2 %

To evaluate the conduction losses use the following equation:

 $P = 0.375 \times I_{F(AV)} + 0.0135 \times I_{F^{2}(RMS)}$

Figure 2. Average forward power dissipation Figure 3. Average forward current versus ambient temperature (per diode) ($\delta = 0.5$, per diode)

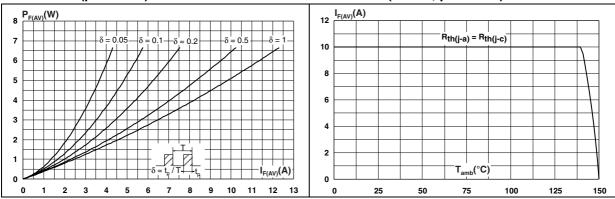
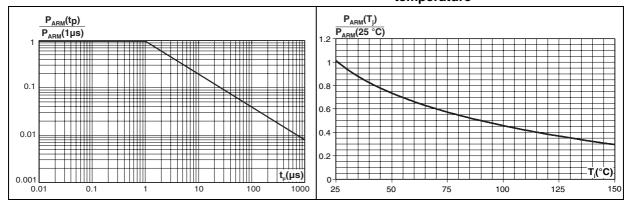


Figure 4. Normalized avalanche power derating versus pulse duration

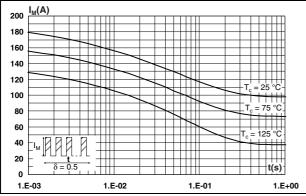
Figure 5. Normalized avalanche power derating versus junction temperature



Characteristics STPS20M60C

Figure 6. Non repetitive surge peak forward current versus overload duration (maximum values, per diode)

Figure 7. Relative thermal impedance junction to case versus pulse duration



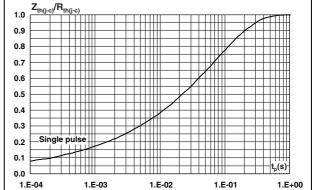
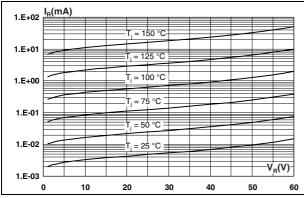


Figure 8. Reverse leakage current versus reverse voltage applied (typical values, per diode)

Figure 9. Junction capacitance versus reverse voltage applied (typical values, per diode)



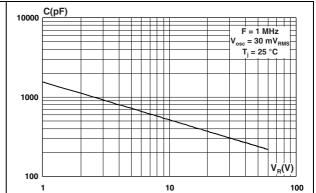
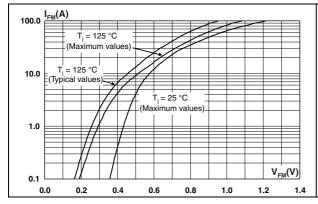
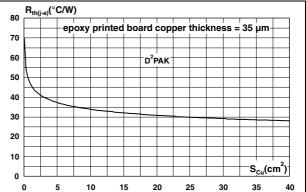


Figure 10. Forward voltage drop versus forward current (per diode)

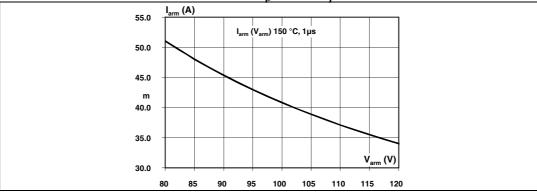
Figure 11. Thermal resistance junction to ambient versus copper surface under tab





STPS20M60C Characteristics

Figure 12. Reverse safe operating area ($t_p < 1 \mu s$, $T_j < 150 °C$)



Package information STPS20M60C

2 Package information

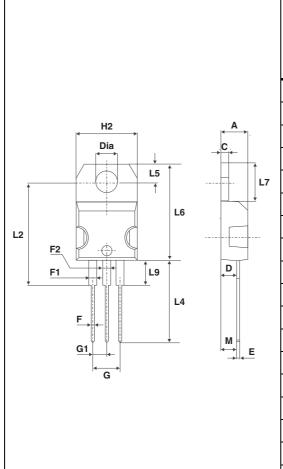
Epoxy meets UL94, V0

Cooling method: by conduction (C)

Recommended torque value: 0.4 to 0.6 N⋅m

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Table 5. TO-220AB dimensions



	Dimensions			
Ref.	Millimeters		Inc	hes
	Min.	Max.	Min.	Max.
Α	4.40	4.60	0.173	0.181
С	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
Е	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
F2	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
G1	2.40	2.70	0.094	0.106
H2	10	10.40	0.393	0.409
L2	16.4	Тур.	0.645 Typ.	
L4	13	14	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
М	2.6 Typ.		0.102	2 Typ.
Dia.	3.75	3.85	0.147	0.151

STPS20M60C Package information

Dimensions

Inches

Max.

0.181

0.106

0.009

0.037

0.067

0.024

0.054

0.368

0.409

0.208

0.624

0.055

0.069

0.126

0.016 typ.

Min.

0.173

0.098

0.001

0.027

0.045

0.017

0.048

0.352

0.393

0.192

0.590

0.050

0.055

0.094

0°

Table 6. D²PAK dimensions

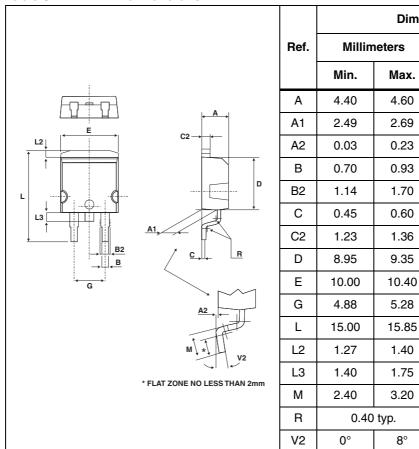
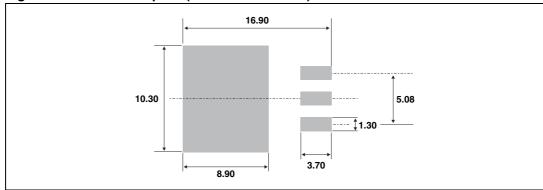
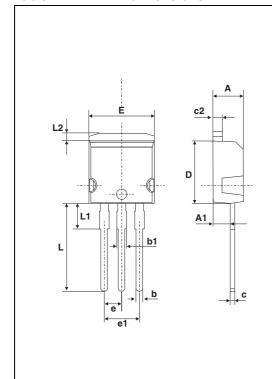


Figure 13. D²PAK footprint (dimensions in mm)



Package information STPS20M60C

Table 7. I²PAK dimensions



	Dimensions			
Ref.	Millim	neters	Inc	hes
	Min.	Max.	Min.	Max.
Α	4.40	4.60	0.173	0.181
A1	2.40	2.72	0.094	0.107
b	0.61	0.88	0.024	0.035
b1	1.14	1.70	0.044	0.067
С	0.49	0.70	0.019	0.028
c2	1.23	1.32	0.048	0.052
D	8.95	9.35	0.352	0.368
е	2.40	2.70	0.094	0.106
e1	4.95	5.15	0.195	0.203
Е	10	10.40	0.394	0.409
L	13	14	0.512	0.551
L1	3.50	3.93	0.138	0.155
L2	1.27	1.40	0.050	0.055

3 Ordering information

Table 8. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS20M60CT	STPS20M60CT	TO-220AB	2.2 g	50	Tube
STPS20M60CR	STPS20M60CR	I ² PAK	1.49 g	50	Tube
STPS20M60CG-TR	STPS20M60CG	D ² PAK	1.48 g	1000	Tape and reel

4 Revision history

Table 9. Revision history

Date	Revision	Changes
14-Oct-2011	1	Initial release.

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